

Performance Comparison of Direct Exception Mode vs Non-Direct Exception Mode on the NS32CG160 Processor

National Semiconductor
Application Note 723
Aharon Ostrer
April 1991



Performance Comparison of Direct Exception Mode vs Non-Direct Exception Mode on the NS32CG160 Processor

1.0 INTRODUCTION

The NS32CG160 is a highly-integrated 32-bit microprocessor specifically optimized for office imaging peripherals and real-time applications.

The NS32CG160 integrates a full 32-bit CPU Core, a 2-channel DMA controller (DMAC), a 16-bit operand BitBLT Processing Unit (BPU), a 15-level Interrupt Control Unit (ICU) and three 16-bit timers, while providing a 16 Mbyte linear address space and a 16-bit external data bus.

Among its features which support office imaging peripheral and real-time applications, is a special Direct-Exception mode. This mode provides fast interrupt service and task switching.

This application note presents the performance comparison between direct and non-direct exception modes as found on the NS32CG160.

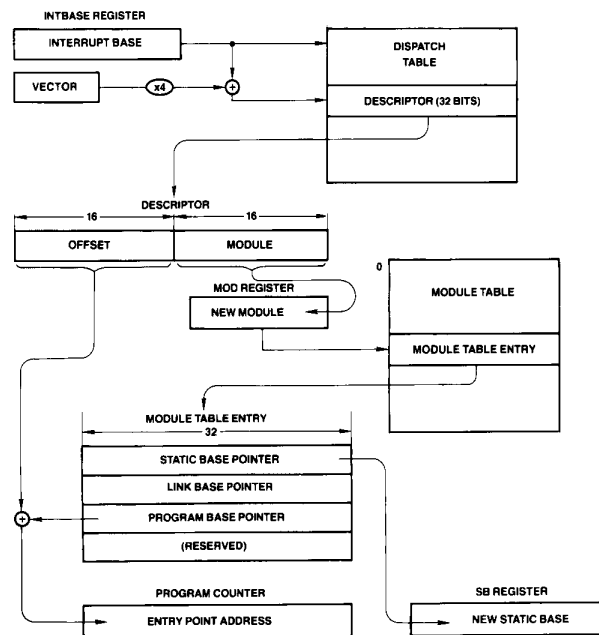
2.0 DESCRIPTION

The NS32CG160 supports two different methods for exception handling. These are known as direct exception mode, and non-direct exception mode. Non-direct exception mode can be used for applications based on modular software. Direct exception mode is preferred for applications which require fast interrupt response and task switching.

The desired exception mode is selected by the value of the Direct Exception (DE) bit in the Configuration Register (CFG). Non-Direct exception mode is enabled by resetting the DE bit ($DE = 0$). Direct exception mode is enabled by setting the DE bit ($DE = 1$). It can only be accessed in supervisor mode.

3.0 NON-DIRECT EXCEPTION MODE

The Non-Direct Exception mode is enabled while the DE bit in the CFG register is 0. In this case the CPU first pushes the saved Program Status Register (PSR) contents along with the contents of the MOD and PC registers onto the Interrupt stack. Then it reads the double-word entry from the Interrupt Dispatch table at address "INTBASE + vector * 4". The CPU uses this entry to call the exception service procedure, interpreting the entry as an external procedure descriptor. A new value number is loaded into the MOD register from the least-significant word of the descriptor, and the Static-Base pointer for the new module is read from the memory and loaded into the SB register. Then the program-base pointer for the new module is read from memory and added to the most-significant word of the module descriptor, which is interpreted as an unsigned value. Finally, the result is loaded into the PC register.

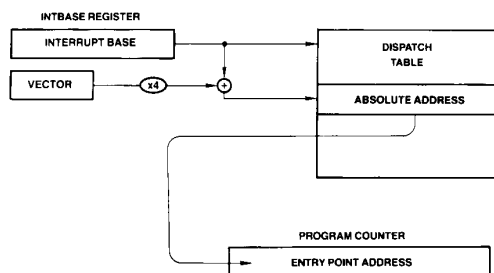


TL/EE/11067-1

FIGURE 1. Non-Direct Exception Mode Exception Handling

AN-723

4.0 DIRECT EXCEPTION MODE



TL/EE/11067-2

FIGURE 2. Direct-Exception Mode Exception Handling

The Direct exception mode is enabled when the DE bit in the CFG register is set to 1. In this case the CPU first pushes the saved PSR contents along with the contents of the PC register onto the Interrupt stack. The 16-bit word stored on the interrupt stack between the saved PSR and PC registers is reserved for future use; its contents is undefined. The CPU then reads the double-word entry from the Interrupt Dispatch table address "INTBASE + vector * 4". The CPU uses this entry to call the exception service procedure, interpreting the entry as an absolute address that is simply loaded into the PC register. The MOD and SB register are not initialized before the CPU transfers control to the service procedure. Consequently, the service procedure is restricted from executing any instruction, such as CXP, that uses the contents of the MOD or SB registers in effective address calculation.

5.0 Performance Comparison

Following is a performance comparison between the Direct and Non-Direct exception modes.

Direct exception mode enables the CPU to respond more quickly to interrupts and other exceptions because fewer memory references are required to process an exception. Direct-Exception Mode also enables faster execution of Return from Interrupt (RETI) and Return from Trap (RETT) instructions. This is because the contents of the MOD and SB are not restored.

A list of the memory references during exception processing as performed by each mode is shown in Table I.

TABLE I. Memory References

Direct-Exception Disabled DE Bit = 0	Direct-Exception Enabled DE Bit = 1
1. Write PSR Copy 2. Write MOD 3. Write High-Word PC 4. Write Low-Word PC 5. Read Low-Word from Dispatch Table 6. Read High-Word from Dispatch Table 7. Read Low-Word SB 8. Read High-Word SB 9. Read Low-Word Program Base 10. Read High-Word Program Base	1. Write PSR Copy 2. Write High-Word PC 3. Write Low-Word PC 4. Read Low-Word from Dispatch Table 5. Read High-Word from Dispatch Table

Table II compares the two modes in terms of Return from Interrupt (RETI) and interrupt latency. The RETI latency is defined as the time in cycles from the End of Interrupt cycle till the fetch of the user instruction. The interrupt latency is defined as the time in cycles from the Interrupt Acknowledge cycle till the fetch of the first instruction in the interrupt handler.

TABLE II. Interrupt/RETI Latency (In Cycles)

	Non-Direct	Direct
Interrupt	67	35
RETI	69	48

LIFE SUPPORT POLICY

NATIONAL'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF NATIONAL SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.



National Semiconductor Corporation
2900 Semiconductor Drive
P.O. Box 58090
Santa Clara, CA 95052-8090
Tel: (408) 272-9959
TWX: (910) 339-9240

National Semiconductor GmbH
Livry-Gargan-Str. 10
D-82256 Fürstentfeldbruck
Germany
Tel: (81-41) 35-0
Telex: 527849
Fax: (81-41) 35-1

National Semiconductor Japan Ltd.
Sumitomo Chemical Engineering Center
Bldg. 7F
1-7-1, Nakase, Mihama-Ku
Chiba-City,
Chiba Prefecture 261
Tel: (043) 299-2300
Fax: (043) 299-2500

National Semiconductor Hong Kong Ltd.
13th Floor, Straight Block,
Ocean Centre, 5 Canton Rd.
Tsimshatsui, Kowloon
Hong Kong
Tel: (852) 2737-1600
Fax: (852) 2736-9960

National Semicondutores Do Brazil Ltda.
Rue Deputado Lacorda Franco
120-3A
Sao Paulo-SP
Brazil 05418-000
Tel: (55-11) 212-5066
Telex: 391-1131931 NSBR BR
Fax: (55-11) 212-1181

National Semiconductor (Australia) Pty. Ltd.
Building 16
Business Park Drive
Monash Business Park
Nottingham, Melbourne
Victoria 3168 Australia
Tel: (3) 558-9999
Fax: (3) 558-9998

National does not assume any responsibility for use of any circuitry described, no circuit patent licenses are implied and National reserves the right at any time without notice to change said circuitry and specifications.